



## Material Content Data Sheet



<b>Sales Product Name</b>		BGA 825L6S E6327		<b>Issued</b>		20. July 2018		
<b>MA#</b>		MA001056000						
<b>Package</b>		PG-TSLP-6-3		<b>Weight*</b>		0.83 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.214	25.94	25.94	259441	259441
bumps	noble metal	silver	7440-22-4	0.000	0.00		17	
	non noble metal	tin	7440-31-5	0.001	0.07		739	
leadframe	non noble metal	copper	7440-50-8	0.006	0.73	0.80	7332	8088
	non noble metal	nickel	7440-02-0	0.110	13.34	13.34	133407	133407
encapsulation	organic material	carbon black	1333-86-4	0.002	0.28		2804	
	plastics	epoxy resin	-	0.067	8.13		81323	
leadfinish	inorganic material	silicondioxide	60676-86-0	0.394	47.69	56.10	476721	560848
	noble metal	gold	7440-57-5	0.011	1.28	1.28	12841	12841
plating	noble metal	silver	7440-22-4	0.021	2.53	2.53	25273	25273
ubm	non noble metal	copper	7440-50-8	0.000	0.01		67	
	non noble metal	titanium	7440-32-6	0.000	0.00		23	
*deviation	non noble metal	tungsten	7440-33-7	0.000	0.00	0.01	12	102
	< 10%			Sum in total:		100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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